



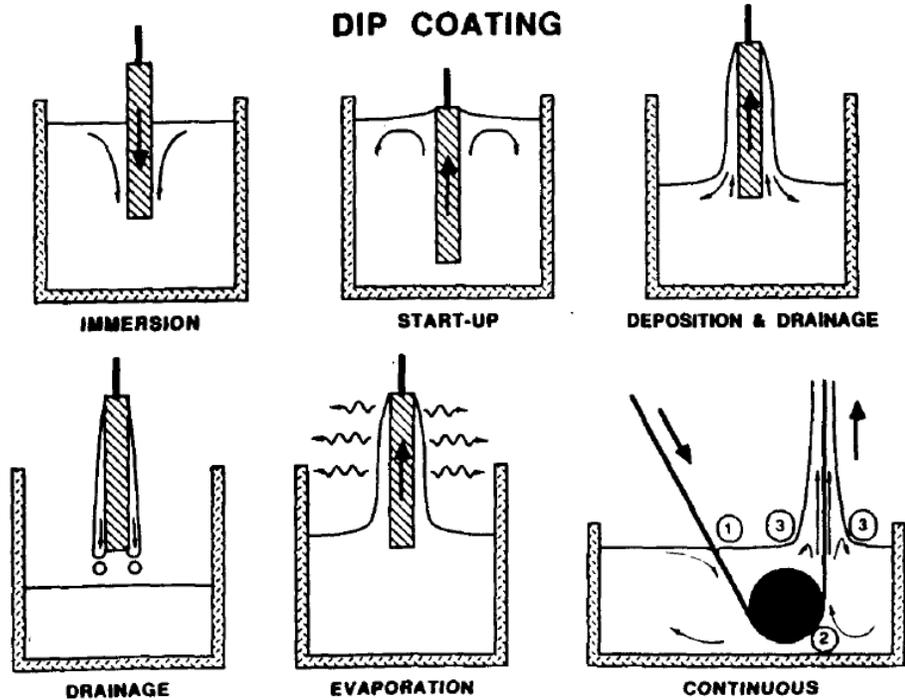
How-To: Spin Processing

JACOB GRANT

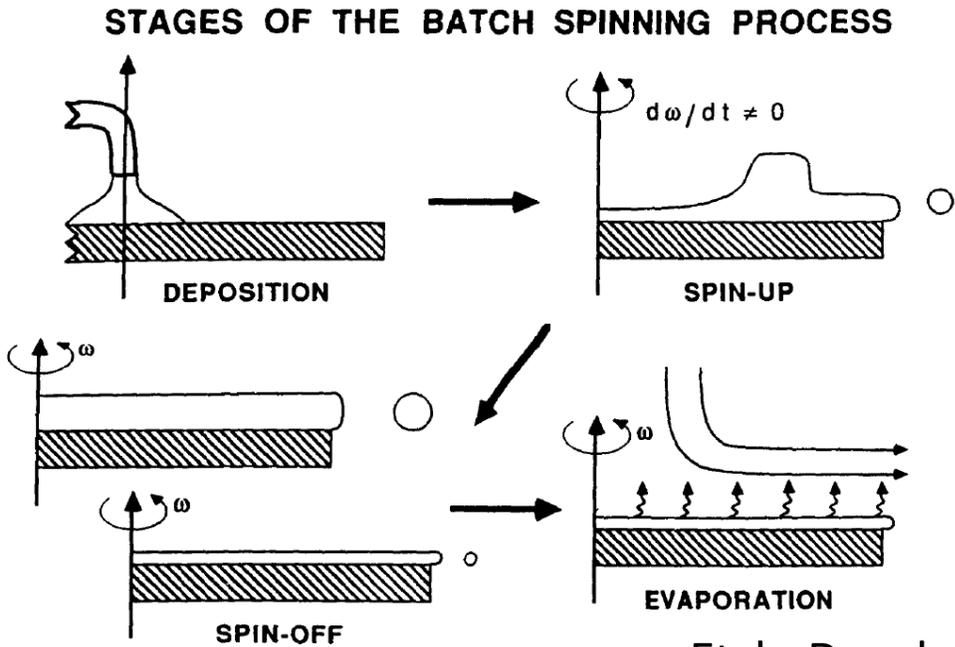
SHAW GROUP MEETING

161006

Dip vs. Spin Coating

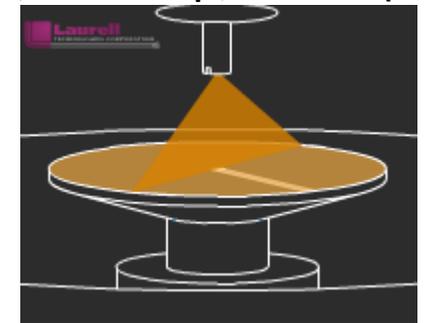
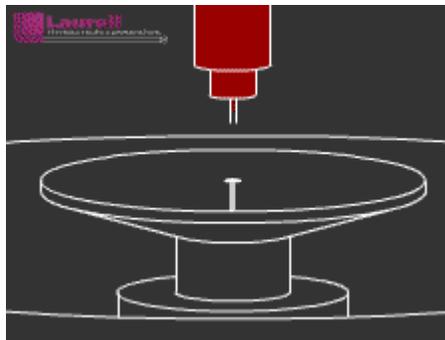


Drainage and evaporation form thin film

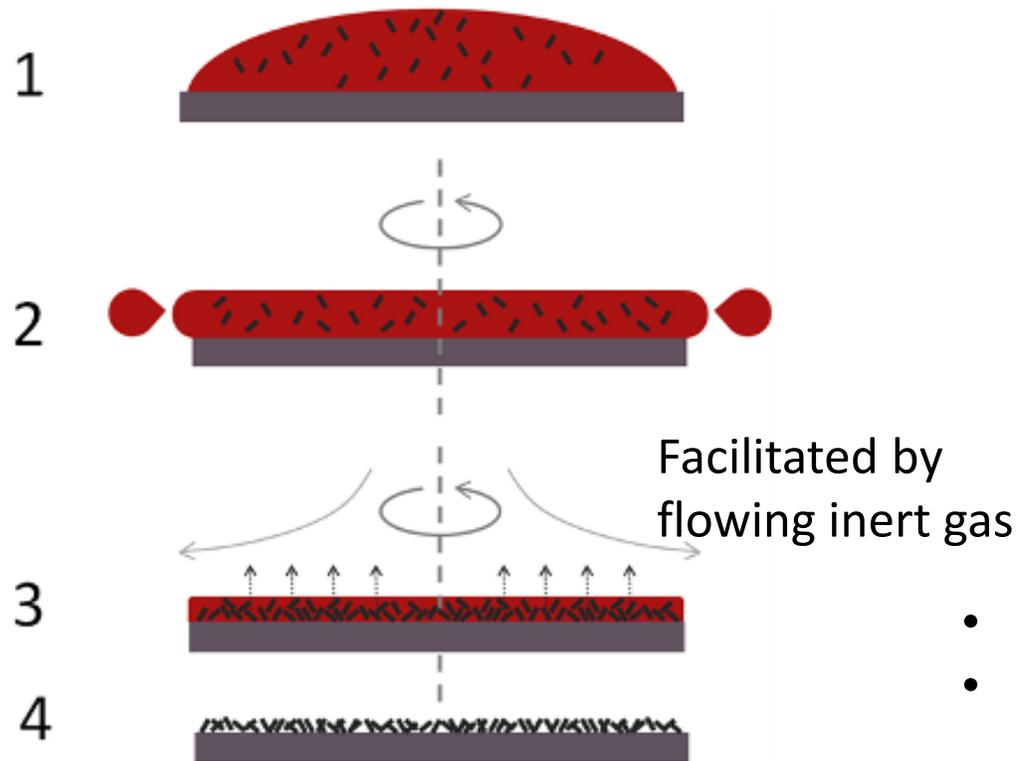


Spin-off and evaporation form thin film

Etch, Develop, Clean (EDC)



Spin Coating Theory



$$h = \left(1 - \rho_A / \rho_{A0} \right) \cdot \left(\frac{3\eta \cdot m}{2\rho_{A0} \omega^2} \right)^{\frac{1}{3}}$$

h = film thickness

ρ = density of volatile liquid

η = viscosity of solution

m = rate of evaporation

ω = rotational velocity

- Centrifugal force drives film formation
- Some variables experimentally determined – difficult to calculate theoretical film thickness
- Trial and error to achieve desired thickness

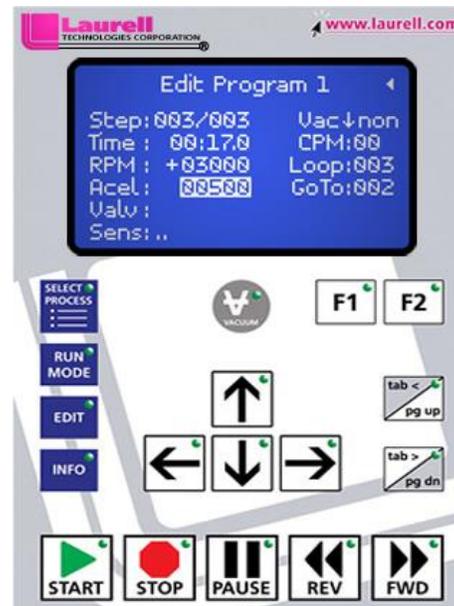
Operation



Chamber (note hole in top for dispensing solvent onto sample)

Sample (resting on stage with vacuum pinhole to immobilize)

Controller



1. Center sample on stage and shut lid (do not open until protocol is complete)
2. Plug controller into outlet to power on
3. Press “Edit” to enter edit mode, use pg up/down keys and arrows to edit your recipe/protocol (# of steps, spin time/speed)
4. Press “Run” to enter run mode, turn on ultrapure nitrogen feed to 60 psi (error “need CDA” will display if nitrogen feed insufficient), plug in vacuum and **press “Vacuum” on controller** (error “need vacuum” will display if not engaged)
5. Press “Start” and wait until protocol is complete, if nitrogen feed or vacuum is interrupted it will stop automatically
6. Unplug vacuum, controller, and turn off nitrogen feed when finished

